### **DESCRIPTION**

The AM2N7002 is available in SOT-23 package.

### **FEATURES**

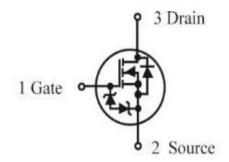
ESD Protected: 1000V

• Available in SOT-23 package

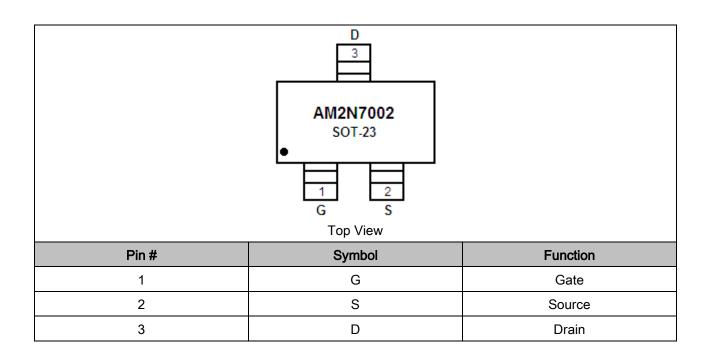
### ORDERING INFORMATION

Package Type	Part Number			
SOT-23	Гэ	AM2N7002E3R		
SPQ: 3,000pcs/Reel	E3	AM2N7002E3VR		
Note	V: Halogen free Package			
Note	R: Tape & Reel			
AiT provides all RoHS products				

### PIN DESCRIPTION



# PIN DESCRIPTION



### **ABSOLUTE MAXIMUM RATINGS**

V <sub>DSS</sub> , Drain-Source Voltage		60Vdc
V <sub>DGR</sub> , Drain-Gate Voltage (R <sub>GS</sub> = 1.0MΩ)		60Vdc
Drain Current		
I <sub>D</sub> , Continuous	T <sub>C</sub> = 25°C	±115mAdc
	T <sub>C</sub> = 100°C	±75mAdc
I <sub>DM</sub> , Pulsed <sup>NOTE1</sup>		±800mAdc
Gate-Source Voltage		
V <sub>GS</sub> , Continuous		±20Vdc
V <sub>GSM</sub> , Non-repetiti	ve (tp ≤ 50µs)	±40Vdc

Stresses above may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated in the Electrical Characteristics are not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

### THERMAL CHARACTERISTICS

Parameter	Symbol	Limits	Unit
Total Device Dissipation FR-5 Board <sup>NOTE2</sup>			
T <sub>A</sub> = 25°C	P <sub>D</sub>	225	mW
Derate above 25°C		1.8	mW/°C
Thermal Resistance, Junction-to-AmbientNOTE2	$R_{\theta JA}$	556	°C/W
Junction and Storage Temperature	TJ, TSTG	-55 to + 150	°C

NOTE1: Pulse Test: Pulse Width ≤ 300µs, Duty Cycle ≤ 2.0%.

NOTE2:  $FR-5 = 1.0 \times 0.75 \times 0.062$  in.

### **ELECTRICAL CHARACTERISTICS**

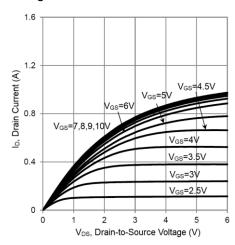
T<sub>A</sub> = 25°C, unless otherwise specified

OFF CHARACTERISTICS Drain-Source Breakdown Voltage	V <sub>BRDSS</sub>							
Drain-Source Breakdown Voltage	V <sub>BRDSS</sub>		OFF CHARACTERISTICS					
Diani Couloc Bicakaowii Voltage		$V_{GS} = 0$ , $I_{D} = 10 \mu Adc$		60	-	-	Vdc	
Zere Oeta Walters Delic Oesa (	I <sub>DSS</sub>	V <sub>GS</sub> = 0,	T <sub>J</sub> = 25°C	-	-	1.0	μAdc	
Zero Gate Voltage Drain Current		V <sub>DS</sub> = 60Vdc	T <sub>J</sub> = 125°C	-	-	500		
Gate-Body Leakage Current,	1	V <sub>GS</sub> = 20Vdc				1.0	u A do	
Forward	I <sub>GSSF</sub>			-	ı	1.0	μAdc	
Gate-Body Leakage Current,	I <sub>GSSR</sub>	\/ = 20\/do			_	1.0	υΛdc	
Reverse	IGSSR	VGS = -20 VUC	$V_{GS} = -20Vdc$		_	-1.0	μAdc	
ON CHARACTERISTICSNOTE3								
Gate Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_D =$	250μAdc	1.0	1.6	2.0	Vdc	
On-State Drain Current	I <sub>D(on)</sub>	$V_{DS} \ge 2.0 V_{DS(or)}$	$V_{DS} \ge 2.0 V_{DS(on)}, V_{GS}=10 Vdc$		-	-	mA	
Static Drain-Source	V <sub>DS(on)</sub>	$V_{GS}$ = 10Vdc, $I_D$ = 500mAdc $V_{GS}$ = 5.0Vdc, $I_D$ = 50mAdc		-	-	3.75	Vdc	
On-State Voltage	▼ DS(on)			-	-	0.375		
		$V_{GS}$ = 10Vdc,	T <sub>C</sub> = 25°C	-	1.4	7.5		
Static Drain-Source	R <sub>DS(ON)</sub>	I <sub>D</sub> = 500mAdc	T <sub>C</sub> = 125°C	-	-	13.5	Ohms	
On- State Resistance	I (DS(ON)	$V_{GS} = 5.0 Vdc$	T <sub>C</sub> = 25°C	-	1.8	7.5	Offilis	
		I <sub>D</sub> = 50mAdc	T <sub>C</sub> = 125°C	-	-	13.5		
Forward Transconductance	G <sub>FS</sub>	V <sub>DS</sub> ≥2.0V <sub>DS(on)</sub> ,I <sub>D</sub> =200mAdc		80	-	-	mmhos	
DYNAMIC CHARACTERISTICS								
Input Capacitance	C <sub>iss</sub>	$V_{DS} = 25V, V_{GS} = 0,$ f = 1.0MHz		-	17	50		
Output Capacitance	Coss			-	10	25	pF	
Reverse Transfer Capacitance	Crss			-	2.5	5.0		
SWITCHING CHARACTERISTICS								
Turn-On Delay Time	t <sub>d(on)</sub>	$V_{DD} = 25 Vdc , I_D = 500 mAdc,$ $R_G = 25 \Omega, R_L = 50 \Omega,$ $V_{gen} = 10 V$		-	7	20	ns	
Turn-Off Delay Time	t <sub>d(off)</sub>			-	11	40	113	
BODY-DRAIN DIODE RATINGS								
Diode Forward On-Voltage	V <sub>SD</sub>	$I_S$ = 115mAdc, $V_{GS}$ = 0V		-	-	-1.5	Vdc	
Source Current Continuous	Is	Body Diode		-	-	-115	mAdc	
Source Current Pulsed	Ism			-	-	-800	mAdc	

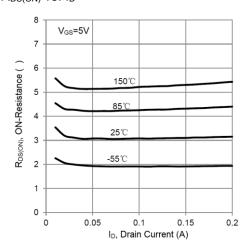
NOTE3: Pulse Test: Pulse Width ≤ 300µs, Duty Cycle ≤ 2.0%.

# TYPICAL PERFORMANCE CHARACTERISTICS

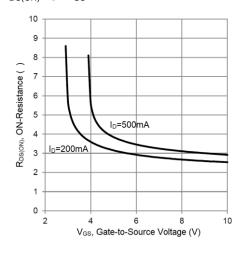
#### 1. ON-Region Characteristics



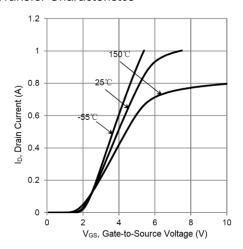
#### 3. $R_{DS(ON)}$ vs. $I_D$



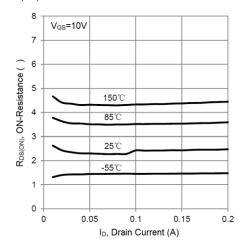
#### 5. RDS(ON) vs. VGS



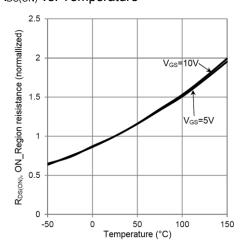
#### 2. Transfer Characteristcs



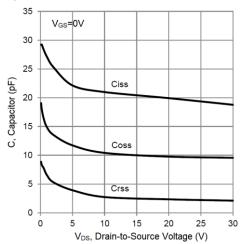
#### 4. $R_{DS(ON)}$ vs. $I_D$



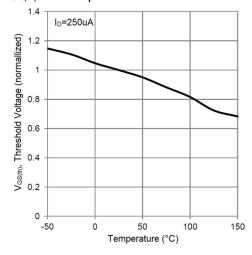
#### 6. R<sub>DS(ON)</sub> vs. Temperature



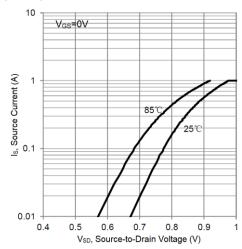
#### 7. Capacitor vs. V<sub>DS</sub>



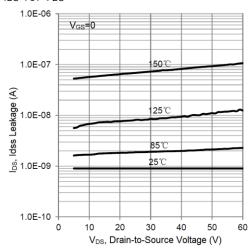
#### 9. $V_{GS(th)}$ vs. Temperature



#### 8. Is vs.VsD

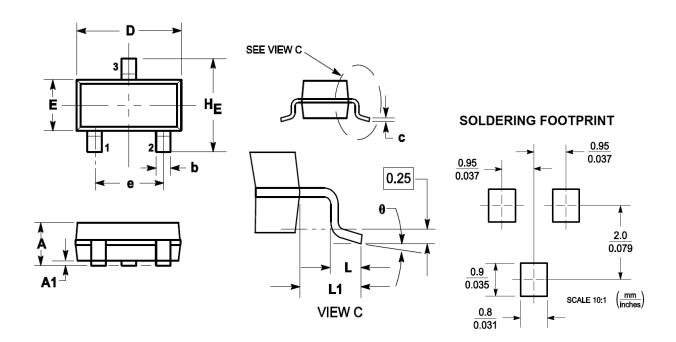


#### $10. \quad I_{DS} \ vs. \ V_{DS}$



# PACKAGE INFORMATION

Dimension in SOT-23 Package (Unit: mm)



Complete	Millim	neters	Inches		
Symbol	Min	Max	Min	Max	
А	0.89	1.11	0.035	0.044	
A1	0.01	0.10	0.001	0.004	
b	0.37	0.50	0.015	0.020	
С	0.09	0.18	0.003	0.007	
D	2.80	3.04	0.110	0.120	
Е	1.20	1.40	0.047	0.055	
е	1.78	2.04	0.070	0.081	
L	0.10	0.30	0.004	0.012	
L1	0.35	0.69	0.014	0.029	
HE	2.10	2.64	0.083	0.104	
θ	0°	10°	0°	10°	

#### IMPORTANT NOTICE

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